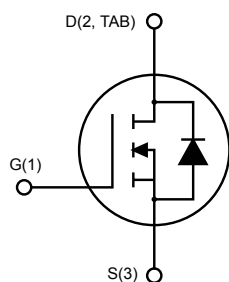
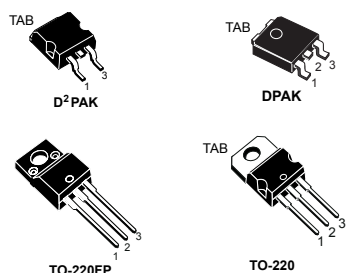


N-channel 200 V, 0.11 Ω , 15 A, MESH OVERLAY™ Power MOSFETs in D²PAK, DPAK, TO-220FP and TO-220 packages



AM01475v1_noZen

Features

Type	V _{DS}	R _{DS(on)} max.	I _D	Package
STB19NF20	200 V	0.16 Ω	15 A	D ² PAK
STD19NF20				DPAK
STF19NF20				TO-220FP
STP19NF20				TO-220

- Extremely high dv/dt capability
- Gate charge minimized
- Very low intrinsic capacitance

Applications

- Switching applications

Description

These Power MOSFETs are designed using STMicroelectronics' consolidated strip-layout-based MESH OVERLAY™ process. The result is a product that matches or improves on the performance of comparable standard parts from other manufacturers.

Product status links

[STB19NF20](#)
[STD19NF20](#)
[STF19NF20](#)
[STP19NF20](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D ² PAK, DPAK, TO-220	TO-220FP	
V_{DS}	Drain-source voltage	200		
V_{GS}	Gate-source voltage	± 20		V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	15	15 ⁽¹⁾	A
	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	9.45	9.45 ⁽¹⁾	
$I_{DM}^{(2)}$	Drain current (pulsed)	60	60 ⁽¹⁾	A
P_{TOT}	Total dissipation at $T_{case} = 25\text{ }^{\circ}\text{C}$	90	25	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1\text{ s}$, $T_C = 25\text{ }^{\circ}\text{C}$)		2.5	kV
$dv/dt^{(3)}$	Peak diode recovery voltage slope	15		V/ns
T_{stg}	Storage temperature range	-55 to 150		$^{\circ}\text{C}$
T_j	Operating junction temperature range			

1. This value is limited by package.
2. Pulse width is limited by safe operating area.
3. $I_{SD} \leq 15\text{ A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} = 80\% V_{(BR)DSS}$

Table 2. Thermal data

Symbol	Parameter	Value				Unit
		D ² PAK	DPAK	TO-220	TO-220FP	
R _{thj-case}	Thermal resistance junction-case	1.39			5	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb	35	50			
R _{thj-amb}	Thermal resistance junction-ambient			62.5		

1. When mounted on an 1-inch² FR-4, 2oz Cu board

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	15	A
E_{AS}	Single-pulse avalanche energy (starting $T_j = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	110	mJ

2 Electrical characteristics

($T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$, $I_{\text{D}} = 1\text{ mA}$	200			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 200\text{ V}$			1	μA
		$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 200\text{ V}$, $T_{\text{C}} = 125\text{ }^{\circ}\text{C}^{(1)}$			10	
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$, $V_{\text{GS}} = \pm 20\text{ V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_{\text{D}} = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$, $I_{\text{D}} = 7.5\text{ A}$		0.11	0.16	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{\text{DS}} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{\text{GS}} = 0\text{ V}$	-	800	-	pF
C_{oss}	Output capacitance		-	165	-	
C_{rss}	Reverse transfer capacitance		-	26	-	
Q_{g}	Total gate charge	$V_{\text{DD}} = 160\text{ V}$, $I_{\text{D}} = 15\text{ A}$, $V_{\text{GS}} = 0\text{ to }10\text{ V}$ (see Figure 16. Test circuit for gate charge behavior)	-	24	-	nC
Q_{gs}	Gate-source charge		-	4.4	-	
Q_{gd}	Gate-drain charge		-	11.6	-	

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 100\text{ V}$, $I_{\text{D}} = 7.5\text{ A}$, $R_{\text{G}} = 4.7\text{ }\Omega$, $V_{\text{GS}} = 10\text{ V}$	-	11.5	-	ns
t_{r}	Rise time		-	22	-	
$t_{\text{d(off)}}$	Turn-off delay time	(see Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	19	-	
t_{f}	Fall time		-	11	-	

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		15	A
$I_{\text{SDM}}^{(1)}$	Source-drain current (pulsed)		-		60	A
$V_{\text{SD}}^{(2)}$	Forward on voltage	$I_{\text{SD}} = 15\text{ A}$, $V_{\text{GS}} = 0\text{ V}$	-		1.6	V

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_{SD} = 15\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 50\text{ V}$ (see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	125		ns
Q_{rr}	Reverse recovery charge		-	0.55		μC
I_{RRM}	Reverse recovery current		-	8.8		A
t_{rr}	Reverse recovery time	$I_{SD} = 15\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 50\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	148		ns
Q_{rr}	Reverse recovery charge		-	0.73		μC
I_{RRM}	Reverse recovery current		-	9.9		A

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for D²PAK, DPAK and TO-220

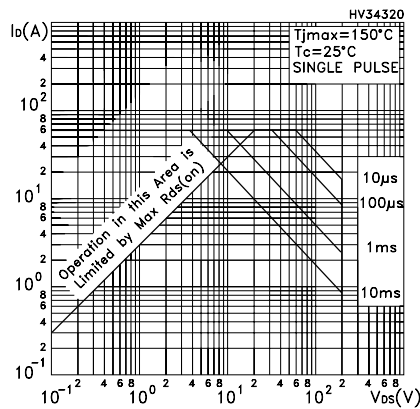


Figure 2. Thermal impedance for D²PAK, DPAK and TO-220

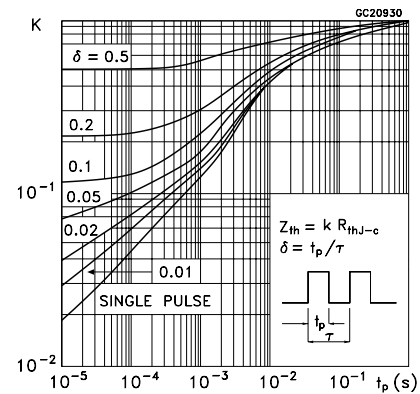


Figure 3. Safe operating area for TO-220FP

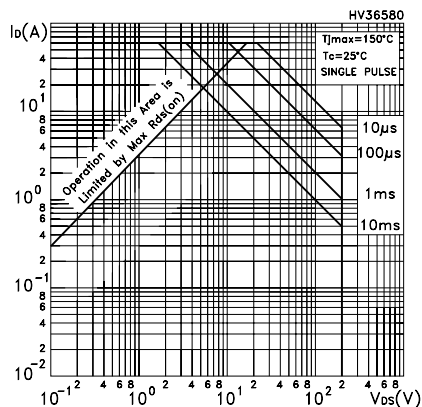


Figure 4. Thermal impedance for TO-220FP

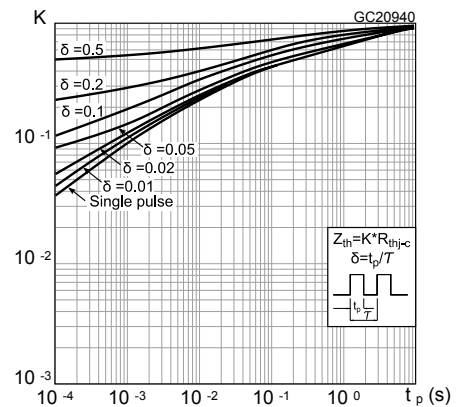


Figure 5. Output characteristics

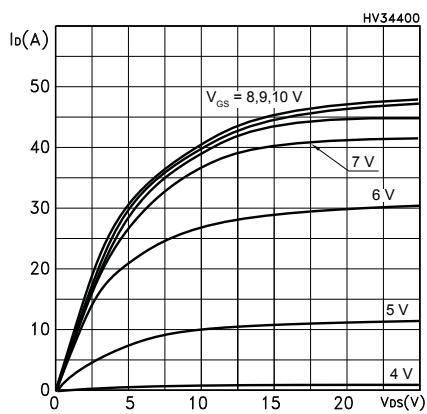


Figure 6. Transfer characteristics

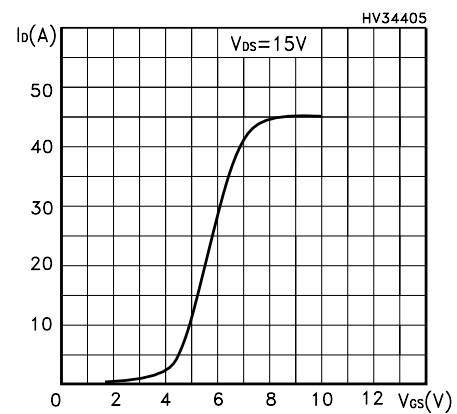


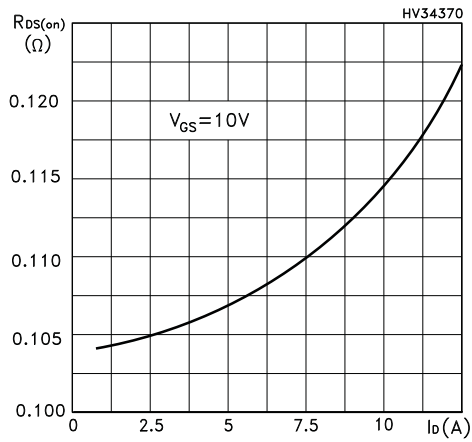
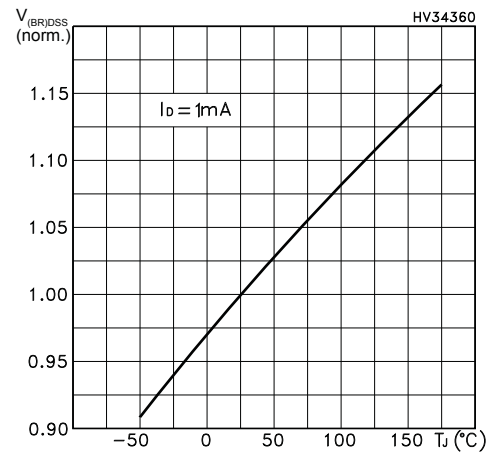
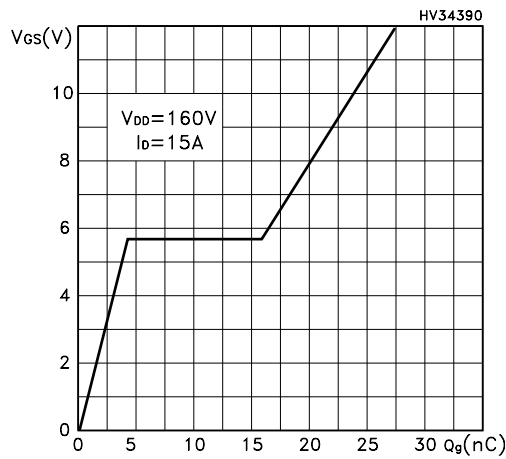
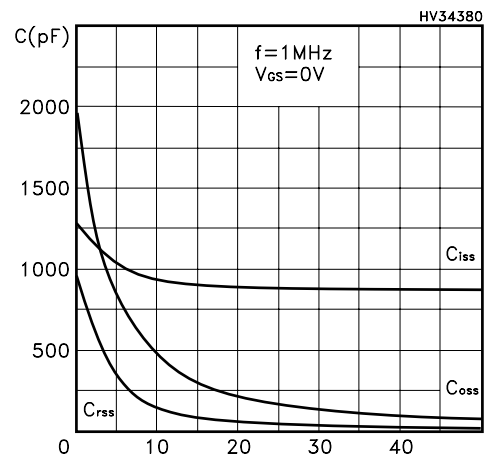
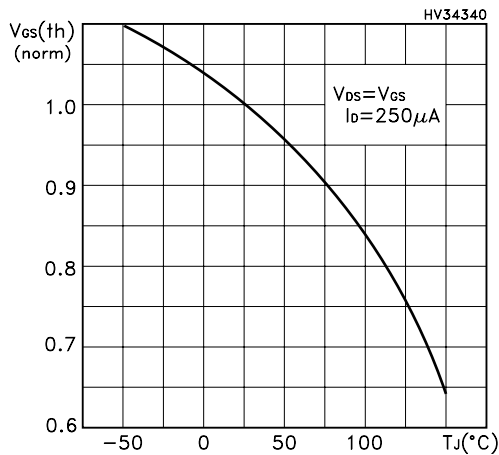
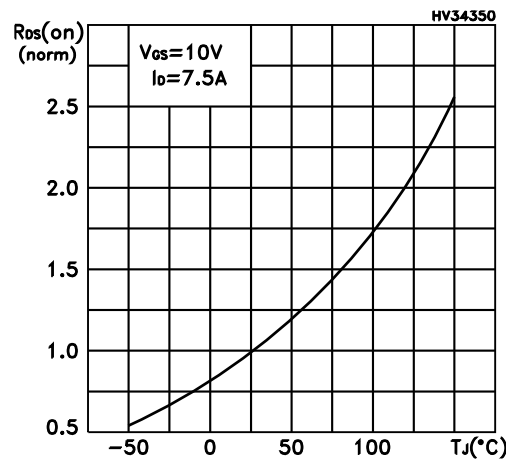
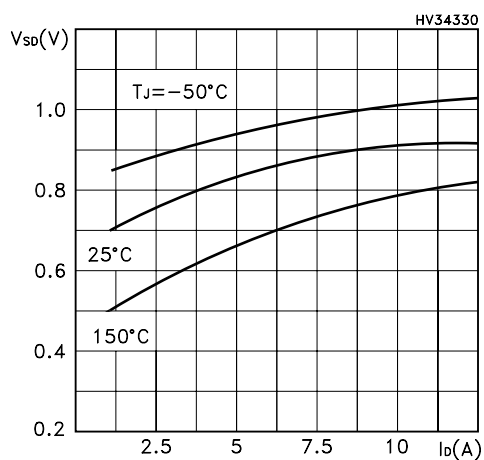
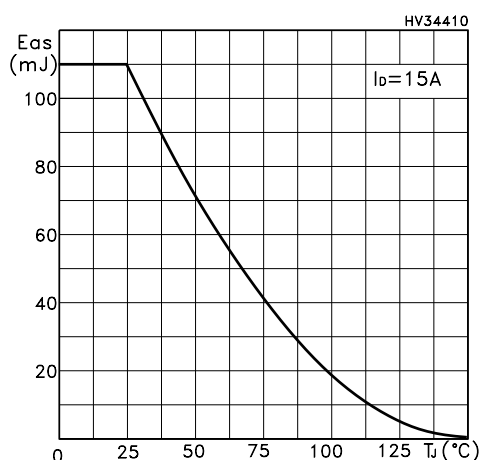
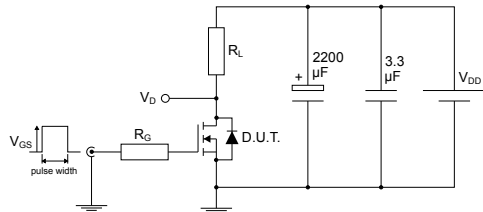
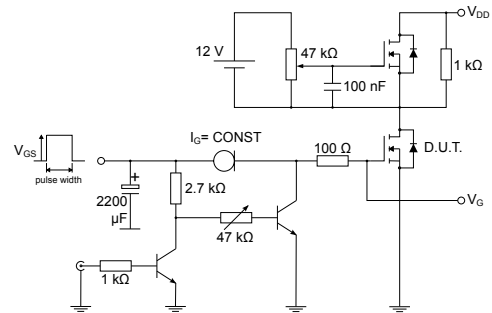
Figure 7. Static drain-source on-resistance

Figure 8. Normalized $V_{(BR)DSS}$ vs temperature

Figure 9. Gate charge vs gate-source voltage

Figure 10. Capacitance variations

Figure 11. Normalized gate threshold voltage vs temperature

Figure 12. Normalized on-resistance vs temperature


Figure 13. Source-drain diode forward characteristics

Figure 14. Maximum avalanche energy vs temperature


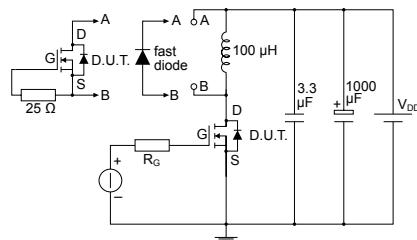
3 Test circuits

Figure 15. Test circuit for resistive load switching times


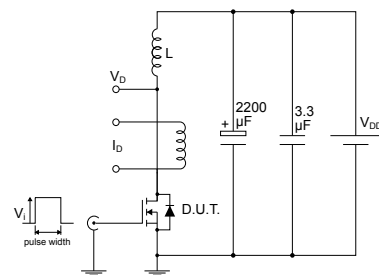
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Figure 16. Test circuit for gate charge behavior


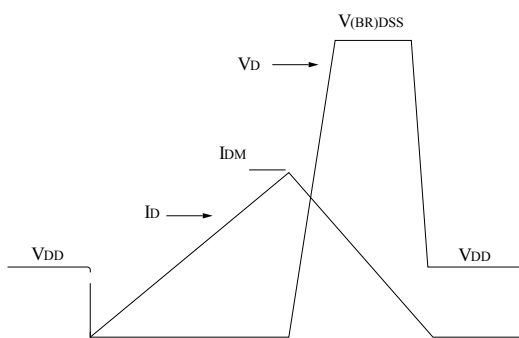
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Figure 17. Test circuit for inductive load switching and diode recovery times


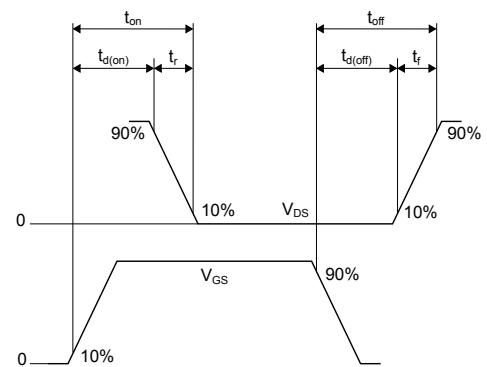
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Figure 18. Unclamped inductive load test circuit


AM01471v1

Figure 19. Unclamped inductive waveform


AM01472v1

Figure 20. Switching time waveform


AM01473v1

4 Ordering information

Table 8. Order codes

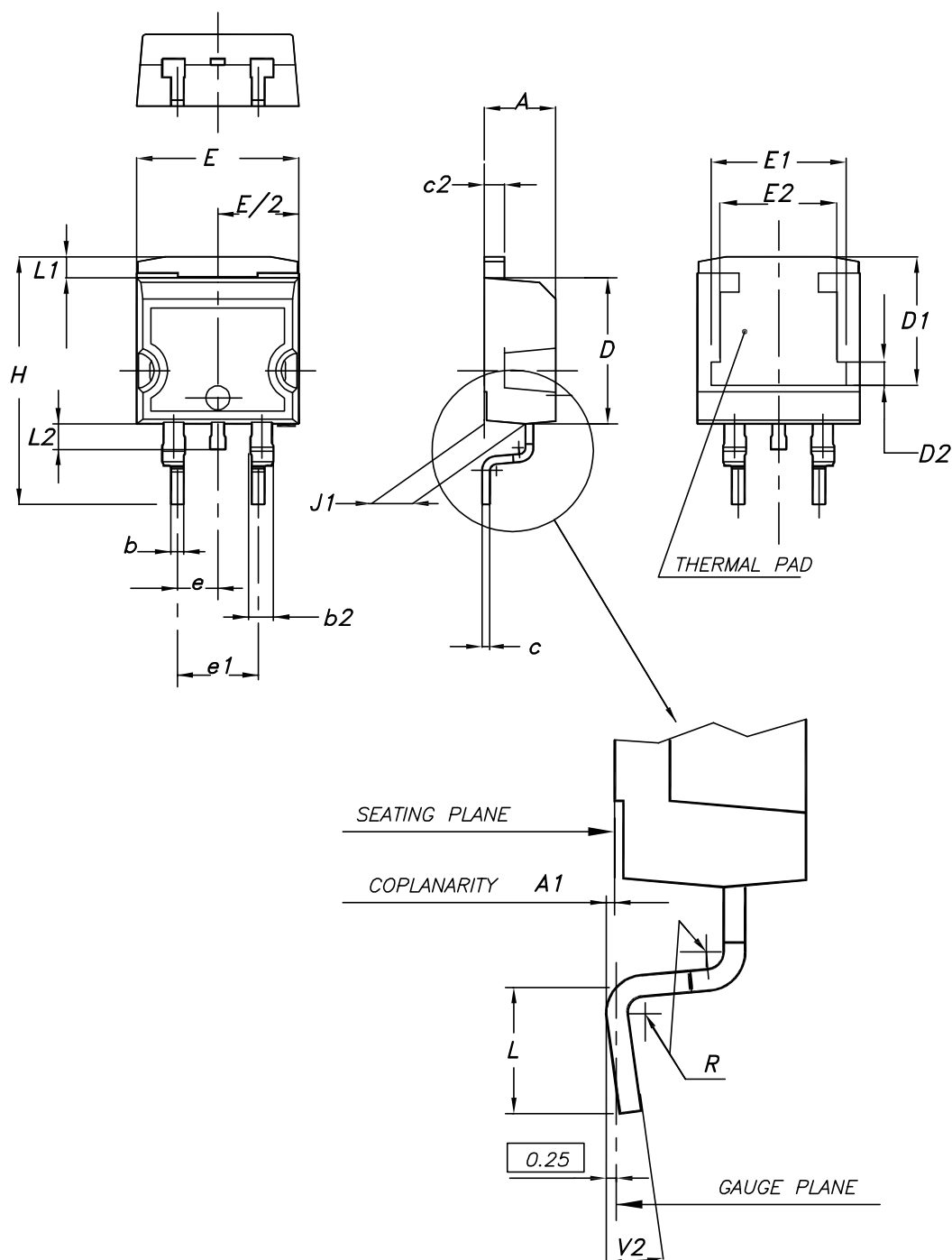
Order code	Marking	Package	Packing
STB19NF20	19NF20	D ² PAK	Tape and reel
STD19NF20		DPAK	
STF19NF20		TO-220FP	Tube
STP19NF20		TO-220	

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

5.1 D²PAK (TO-263) type A package information

Figure 21. D²PAK (TO-263) type A package outline



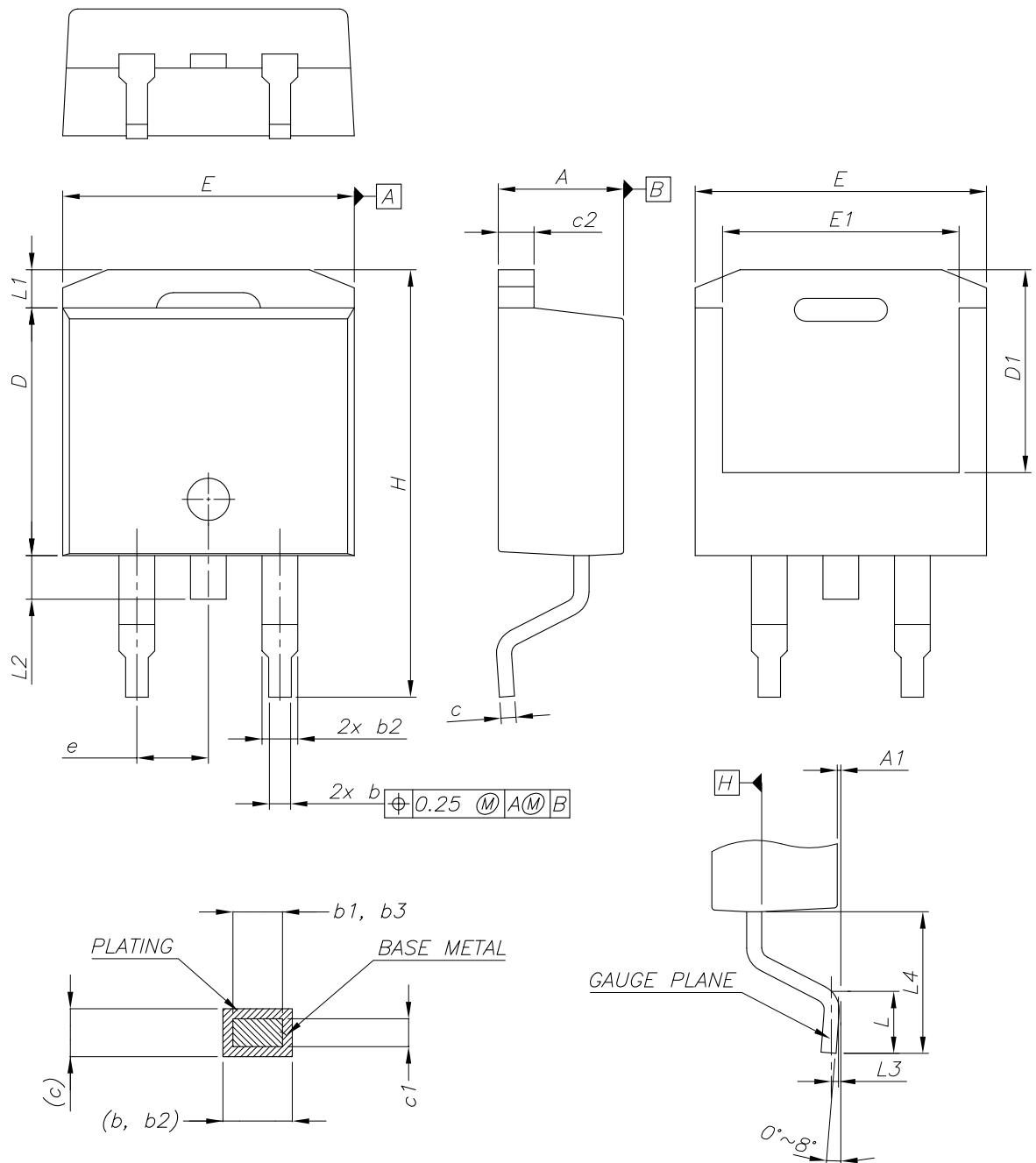
0079457_25

Table 9. D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

5.2 D²PAK (TO-263) type B package information

Figure 22. D²PAK (TO-263) type B package outline

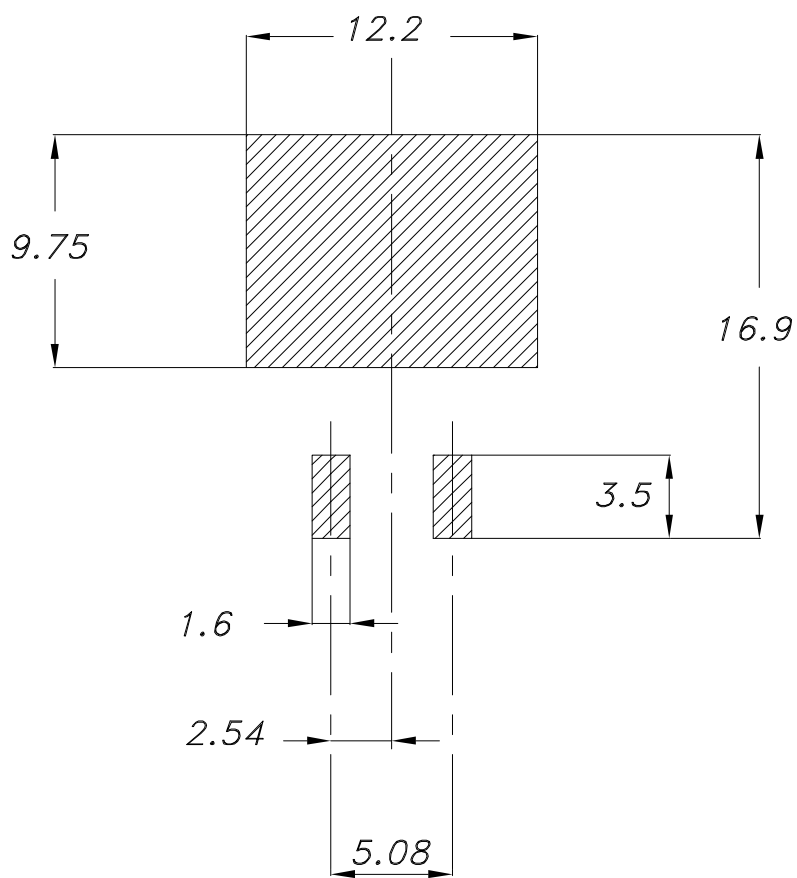


0079457_25_B

Table 10. D²PAK (TO-263) type B mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.36		4.56
A1	0		0.25
b	0.70		0.90
b1	0.51		0.89
b2	1.17		1.37
b3	1.36		1.46
c	0.38		0.694
c1	0.38		0.534
c2	1.19		1.34
D	8.60		9.00
D1	6.90		7.50
E	10.15		10.55
E1	8.10		8.70
e	2.54 BSC		
H	15.00		15.60
L	1.90		2.50
L1			1.65
L2			1.78
L3		0.25	
L4	4.78		5.28

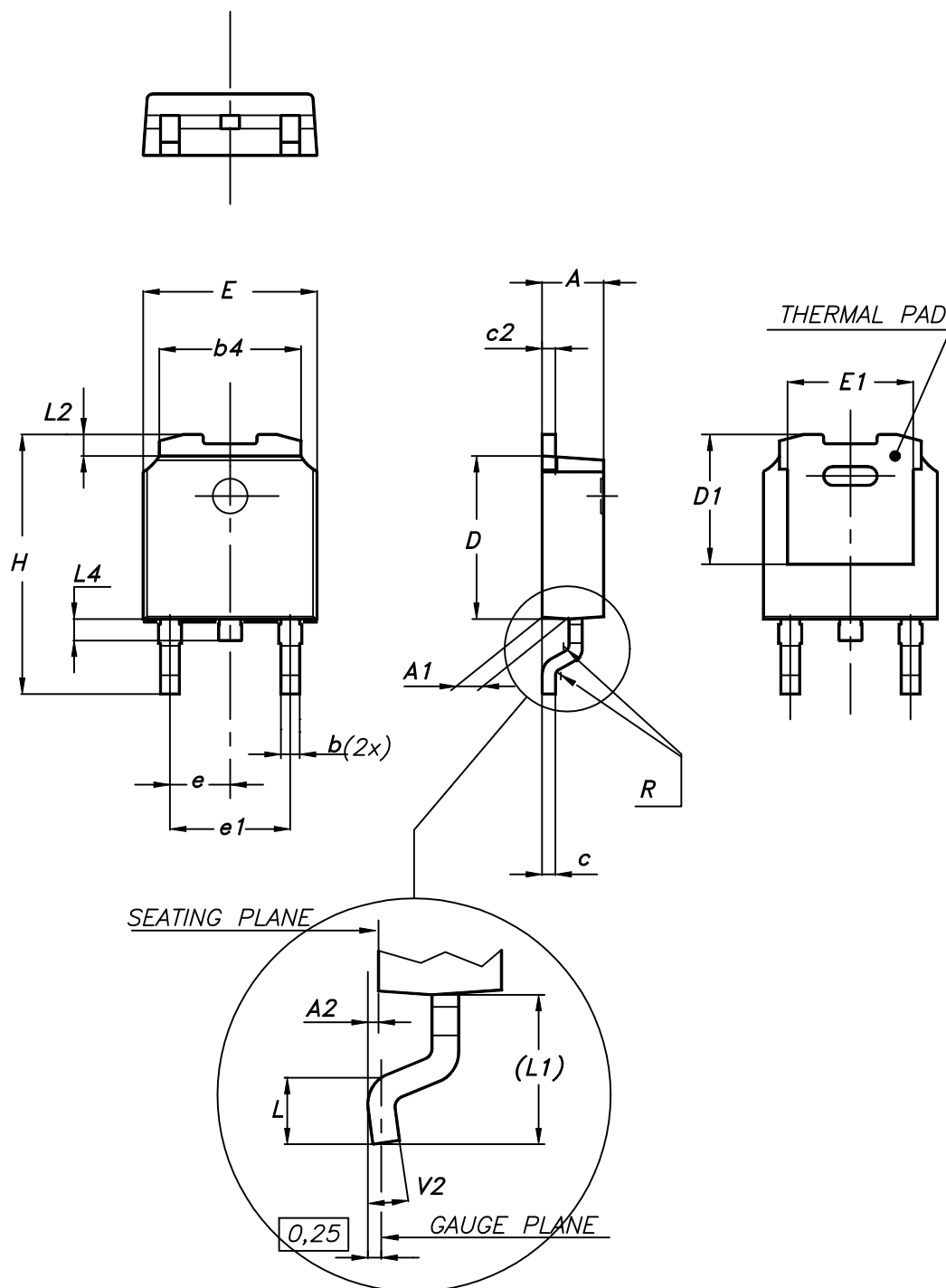
Figure 23. D²PAK (TO-263) recommended footprint (dimensions are in mm)



Footprint

5.3 DPAK (TO-252) type A2 package information

Figure 24. DPAK (TO-252) type A2 package outline



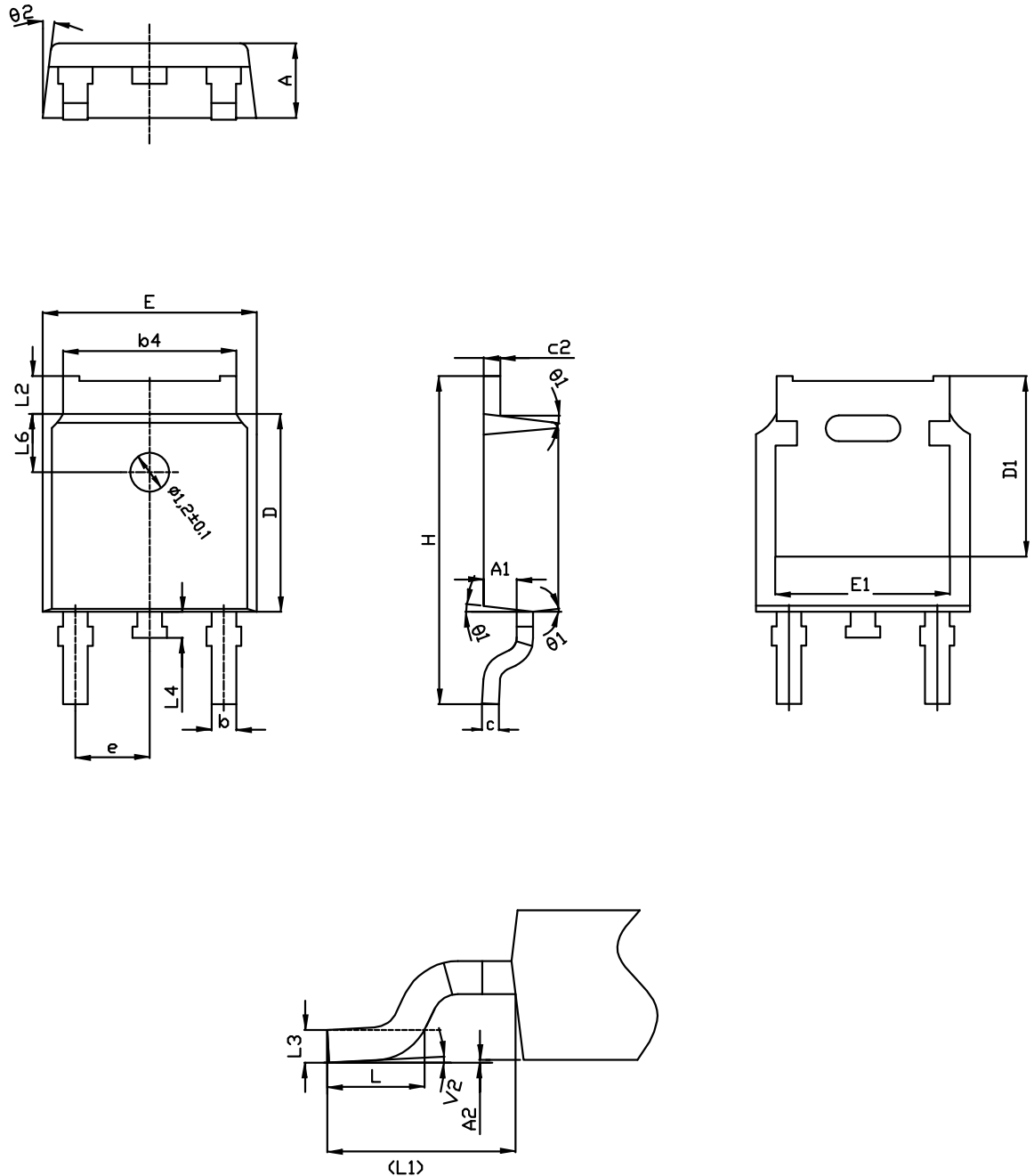
0068772_type-A2_rev25

Table 11. DPAK (TO-252) type A2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

5.4 DPAK (TO-252) type C2 package information

Figure 25. DPAK (TO-252) type C2 package outline

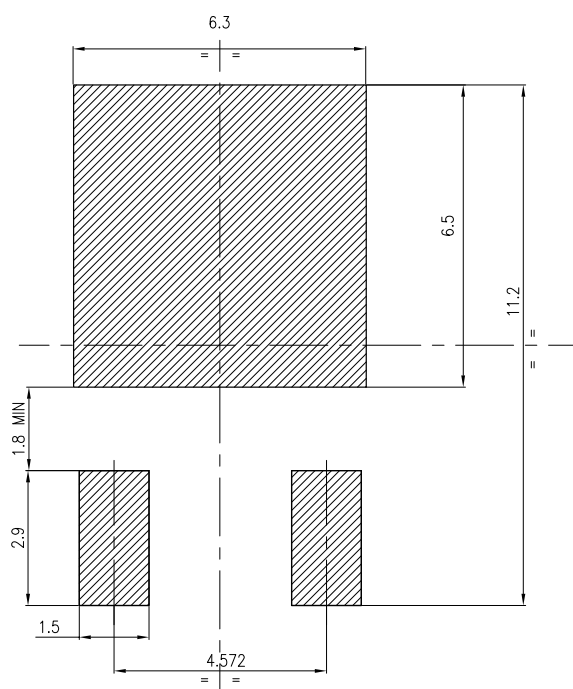


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Table 12. DPAK (TO-252) type C2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

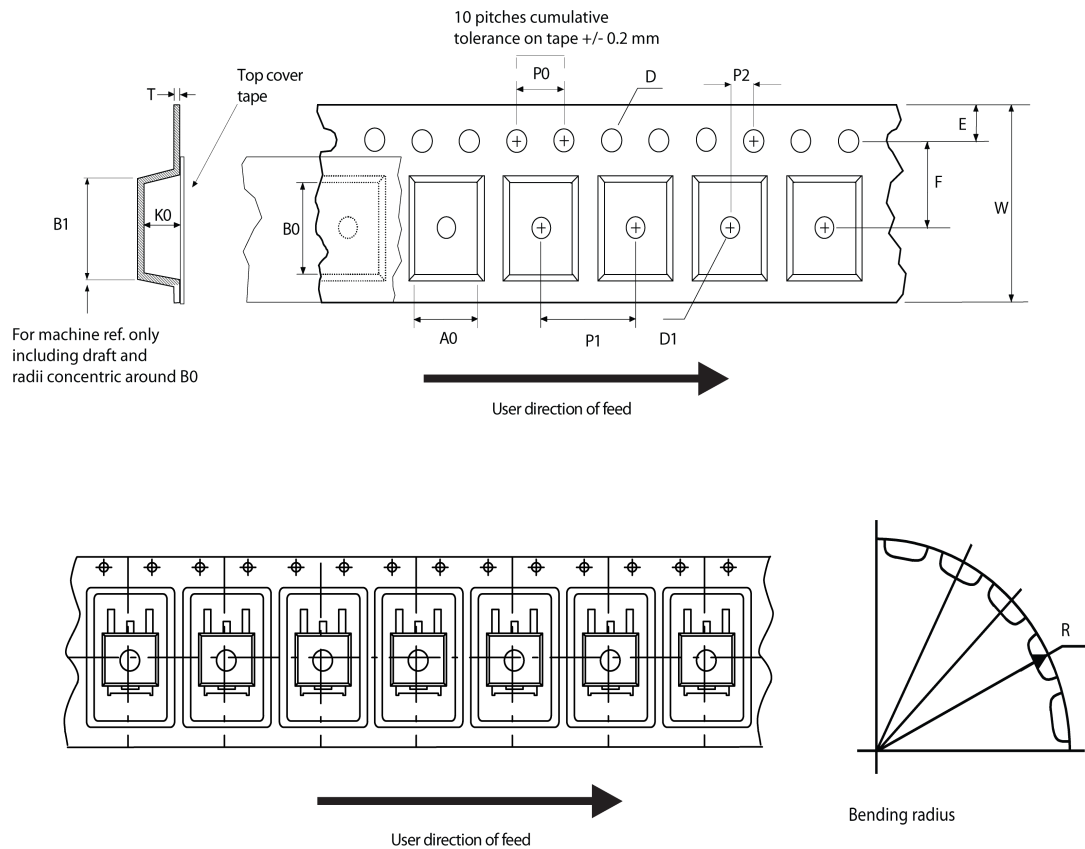
Figure 26. PAK (TO-252) recommended footprint (dimensions are in mm)



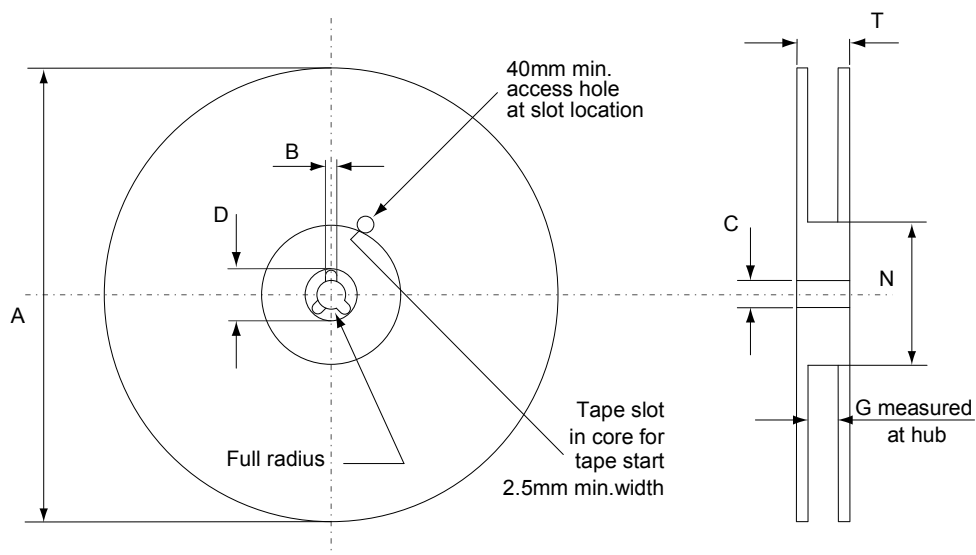
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5.5 D²PAK and DPAK packing information

Figure 27. Tape outline



AM08852v1

Figure 28. Reel outline


AM06038v1

Table 13. D²PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Table 14. DPAK tape and reel mechanical data

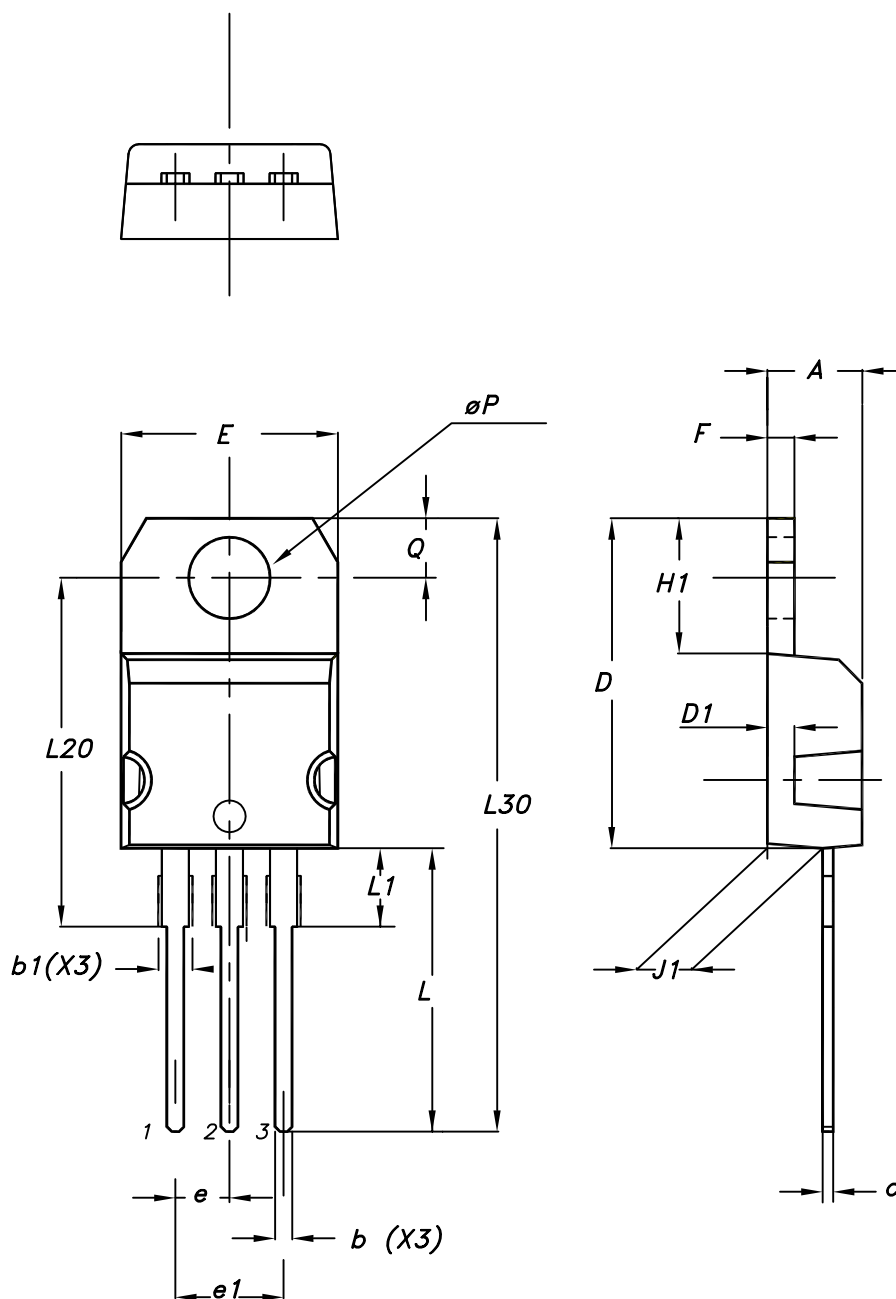
Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Table 15. TO-220FP package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

5.7 TO-220 type A package information

Figure 30. TO-220 type A package outline



0015988_typeA_Rev_21

Table 16. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

Revision history

Table 17. Document revision history

Date	Version	Changes
13-Oct-2006	1	First release.
17-Nov-2006	2	Part number has been modified.
02-Feb-2007	3	Preliminary version.
16-Feb-2007	4	TO-220FP package has been added.
15-Oct-2012	5	Updated <i>Section 4: Package information</i> and <i>Section 4: Package information</i> . Minor text changes.
16-Apr-2015	6	Throughout document: – added DPAK package information – text and formatting updates Updated <i>Figure 1: Internal schematic diagram</i> Updated <i>Table 2: Absolute maximum ratings</i> Updated <i>Table 3: Thermal data</i> Updated and renamed <i>Table 5: Static</i> (was On/off states)
09-Aug-2018	7	Removed maturity status indication from cover page. The document status is production data. Updated Table 5. Dynamic . Updated Section 5 Package information . Minor text changes

Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics (curves)	5
3	Test circuits	8
4	Ordering information	9
5	Package information	10
5.1	D ² PAK (TO-263) type A package information	10
5.2	D ² PAK (TO-263) type B package information	12
5.3	DPAK (TO-252) type A2 package information	15
5.4	DPAK (TO-252) type C2 package information	17
5.5	D ² PAK and DPAK packing information	20
5.6	TO-220FP package information	23
5.7	TO-220 type A package information	25
	Revision history	28

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